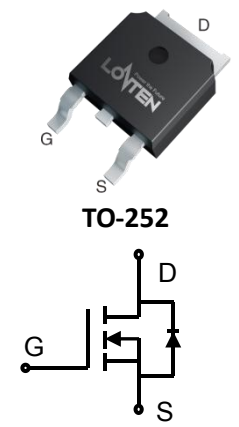


## Lonten N-channel 500V, 5A Power MOSFET

<p><b>Description</b></p> <p>The Power MOSFET is fabricated using the advanced planar <b>VDMOS</b> technology. The resulting device has low conduction resistance, superior switching performance and high avalanche energy.</p> <p><b>Features</b></p> <ul style="list-style-type: none"> <li>● Low <math>R_{DS(on)}</math></li> <li>● Low gate charge (typ. <math>Q_g = 13.2nC</math>)</li> <li>● 100% UIS tested</li> <li>● RoHS compliant</li> </ul> <p><b>Applications</b></p> <ul style="list-style-type: none"> <li>● Power factor correction.</li> <li>● Switched mode power supplies.</li> <li>● LED driver.</li> </ul>	<p><b>Product Summary</b></p> <table> <tr> <td><math>V_{DSS}</math></td><td>500V</td></tr> <tr> <td><math>I_D</math></td><td>5A</td></tr> <tr> <td><math>R_{DS(on),max}</math></td><td>1.6<math>\Omega</math></td></tr> <tr> <td><math>Q_{g,typ}</math></td><td>13.2nC</td></tr> </table> <p><b>Pin Configuration</b></p>  <p style="text-align: center;">TO-252</p> <p style="text-align: center;">N-Channel MOSFET</p>	$V_{DSS}$	500V	$I_D$	5A	$R_{DS(on),max}$	1.6 $\Omega$	$Q_{g,typ}$	13.2nC
$V_{DSS}$	500V								
$I_D$	5A								
$R_{DS(on),max}$	1.6 $\Omega$								
$Q_{g,typ}$	13.2nC								

### Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DSS}$	500	V
Continuous drain current <sup>1)</sup> ( $T_C = 25^{\circ}C$ ) ( $T_C = 100^{\circ}C$ )	$I_D$	5	A
		3	A
Pulsed drain current <sup>2)</sup>	$I_{DM}$	20	A
Gate-Source voltage	$V_{GSS}$	$\pm 30$	V
Avalanche energy, single pulse <sup>3)</sup>	$E_{AS}$	211	mJ
Power Dissipation	$P_D$	80	W
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	$^{\circ}C$
Continuous diode forward current	$I_S$	5	A
Diode pulse current	$I_{S,pulse}$	50	A

### Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.57	$^{\circ}C/W$
Thermal Resistance, Junction-to-Ambient <sup>4)</sup>	$R_{\theta JA}$	96.05	$^{\circ}C/W$
Soldering temperature, wavesoldering only allowed at leads. (1.6mm from case for 10s)	$T_{sold}$	260	$^{\circ}C$

**Package Marking and Ordering Information**

Device	Device Package	Marking	Units/Reel
LNG5N50	TO-252	LNG5N50	2500

**Electrical Characteristics**
 $T_c = 25^{\circ}\text{C}$  unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static characteristics						
Drain-source breakdown voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =0.25mA	500	-	-	V
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =0.25mA	2.0	-	4.0	V
Drain cut-off current	I <sub>DSS</sub>	V <sub>DS</sub> =500V, V <sub>GS</sub> =0 V, T <sub>j</sub> = 25°C	-	-	1	μA
Gate leakage current, Forward	I <sub>GSSF</sub>	V <sub>GS</sub> =20V, V <sub>DS</sub> =0V	-	-	100	nA
Gate leakage current, Reverse	I <sub>GSSR</sub>	V <sub>GS</sub> =-20V, V <sub>DS</sub> =0V	-	-	-100	nA
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10 V, I <sub>D</sub> =2.5A	-	1.38	1.6	Ω
		T <sub>j</sub> = 25°C	-	3.17		
		T <sub>j</sub> = 150°C	-			
Dynamic characteristics						
Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0 V, f = 250kHz	-	549.83	-	pF
Output capacitance	C <sub>oss</sub>		-	56.73	-	
Reverse transfer capacitance	C <sub>rss</sub>		-	2.93	-	
Turn-on delay time	t <sub>d(on)</sub>	V <sub>DD</sub> = 250V, I <sub>D</sub> = 5A R <sub>G</sub> = 10Ω, V <sub>GS</sub> =10V	-	37.9	-	ns
Rise time	t <sub>r</sub>		-	7.2	-	
Turn-off delay time	t <sub>d(off)</sub>		-	18.0	-	
Fall time	t <sub>f</sub>		-	8.1	-	
Gate charge characteristics						
Gate to source charge	Q <sub>gs</sub>	V <sub>DD</sub> =400V, I <sub>D</sub> =2.5A V <sub>GS</sub> =0 to 10V	-	2.6	-	nC
Gate to drain charge	Q <sub>gd</sub>		-	5.8	-	
Gate charge total	Q <sub>g</sub>		-	13.2	-	
Gate plateau voltage	V <sub>plateau</sub>		-	4.7	-	V
Reverse diode characteristics						
Diode forward voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>F</sub> =5A	-	-	1.3	V
Reverse recovery time	t <sub>rr</sub>	V <sub>R</sub> =250V, I <sub>F</sub> =2.5A, dI <sub>F</sub> /dt=100 A/μs	-	201.4	-	ns
Reverse recovery charge	Q <sub>rr</sub>		-	832.8	-	μC
Peak reverse recovery current	I <sub>rrm</sub>		-	6.89	-	A

**Notes:**

1. Drain current limited by maximum junction temperature.
2. Repetitive Rating: Pulse width limited by maximum junction temperature.
3.  $I_{AS}=6.5A, L=10mH, V_{DD}=60V$ , Starting  $T_j=25^{\circ}\text{C}$ .
4. The value of  $R_{thJA}$  is measured by placing the device in a still air box which is one cubic foot.

## Electrical Characteristics Diagrams

Figure 1. Typ. Output Characteristics

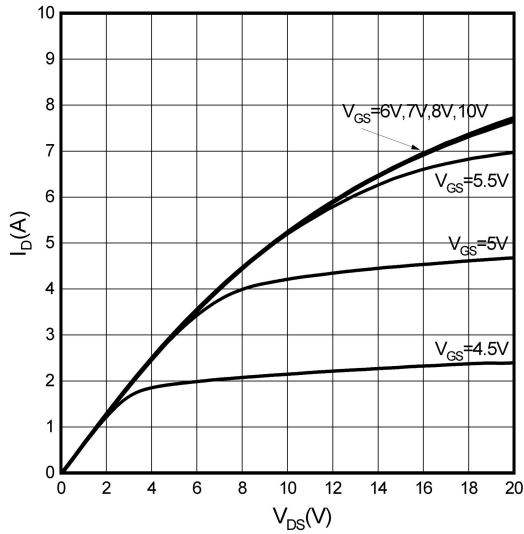


Figure 2. Transfer Characteristics

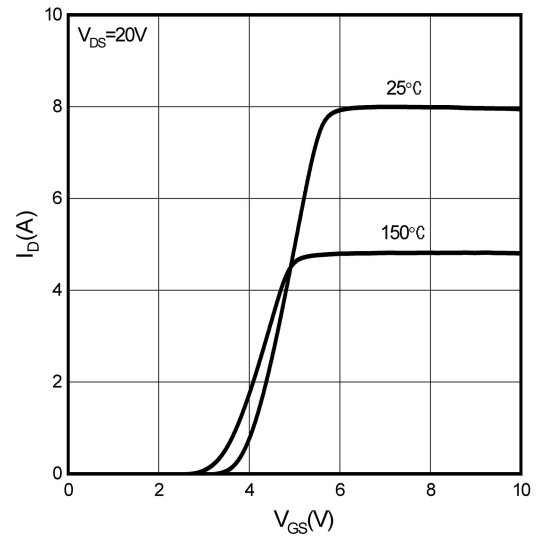


Figure 3. On-Resistance vs. Drain Current

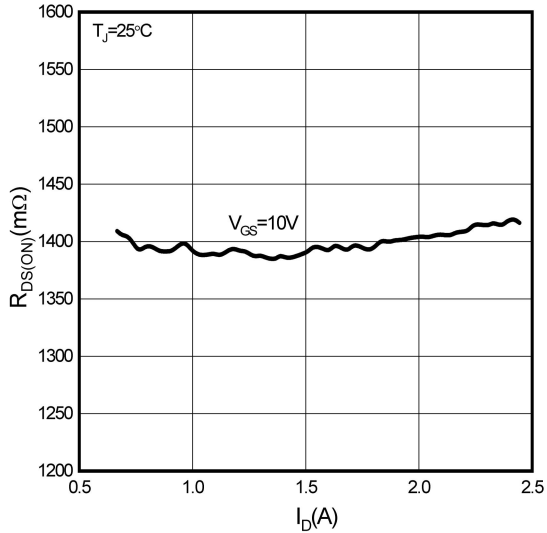


Figure 4. On-Resistance vs. Temperature

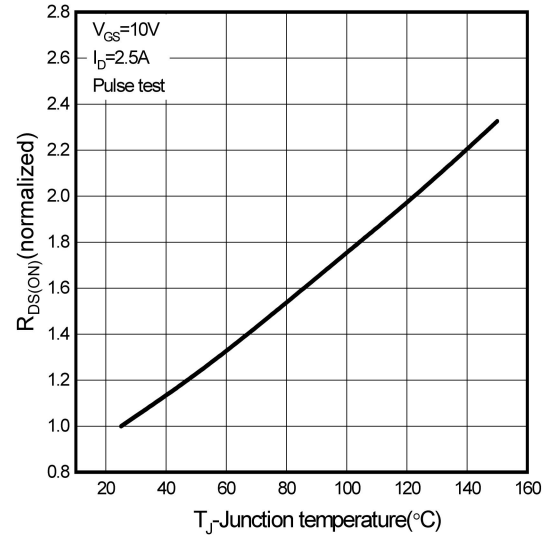


Figure 5. Breakdown Voltage vs. Temperature

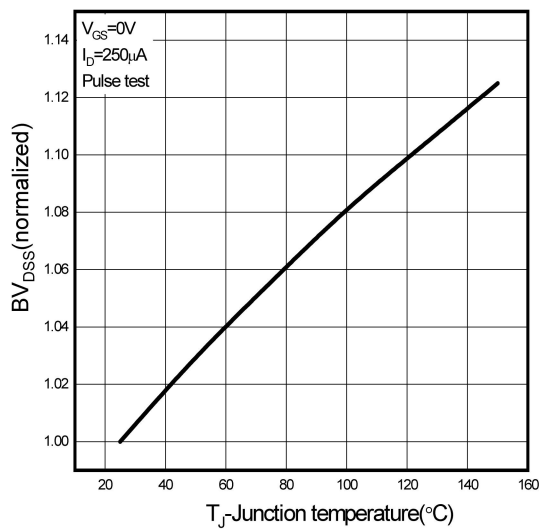


Figure 6. Threshold Voltage vs. Temperature

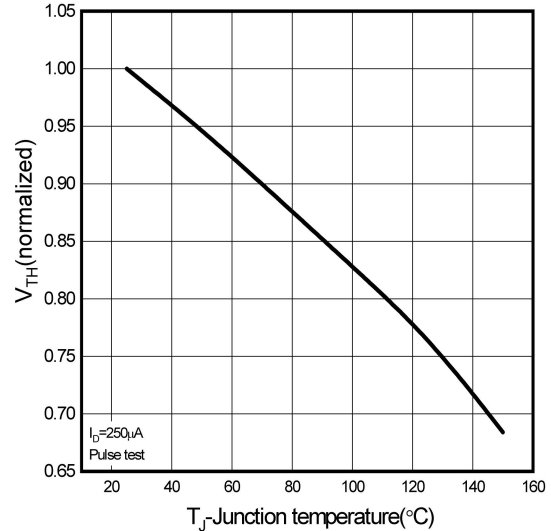


Figure 7.  $R_{DS(on)}$  vs. Gate Voltage

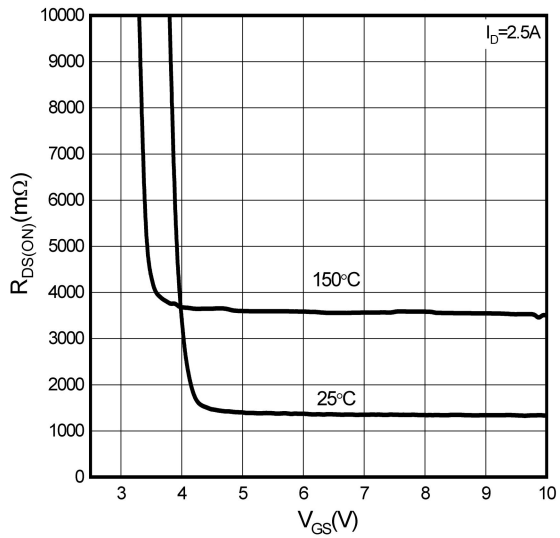


Figure 8. Body-Diode Characteristics

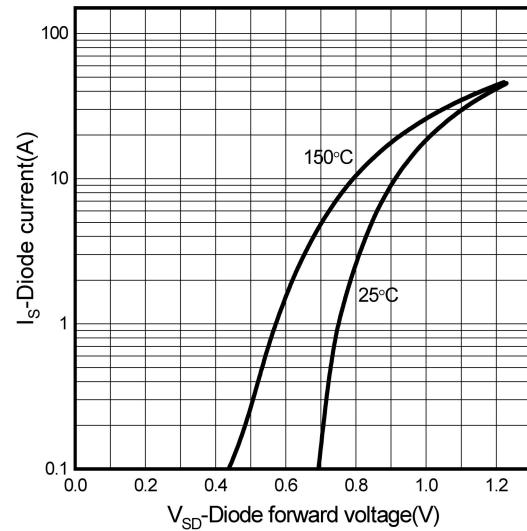


Figure 9. Capacitance Characteristics

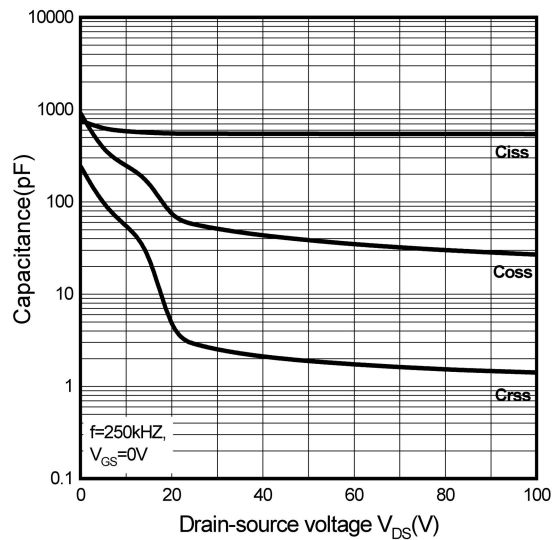


Figure 10. Gate Charge Characteristics

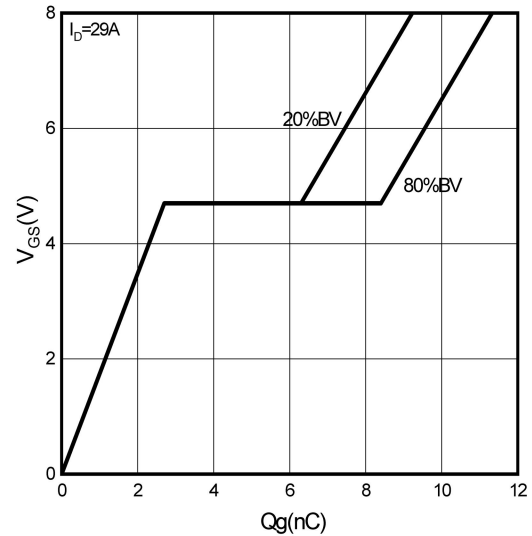


Figure 11. Drain Current Derating

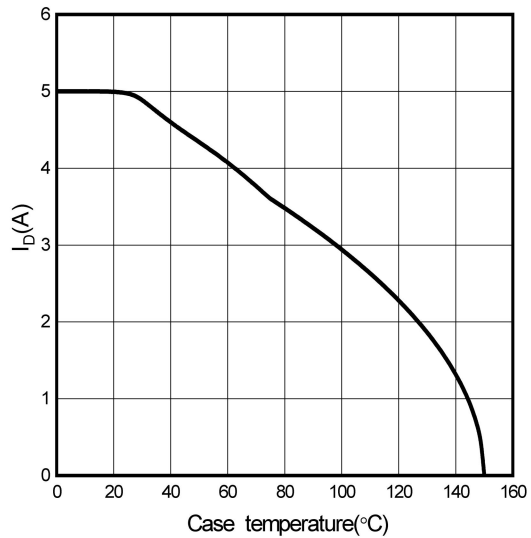


Figure 12. Power Dissipation vs. Temperature

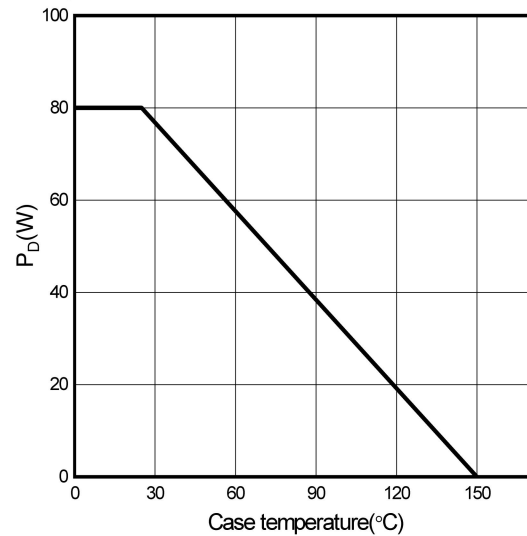
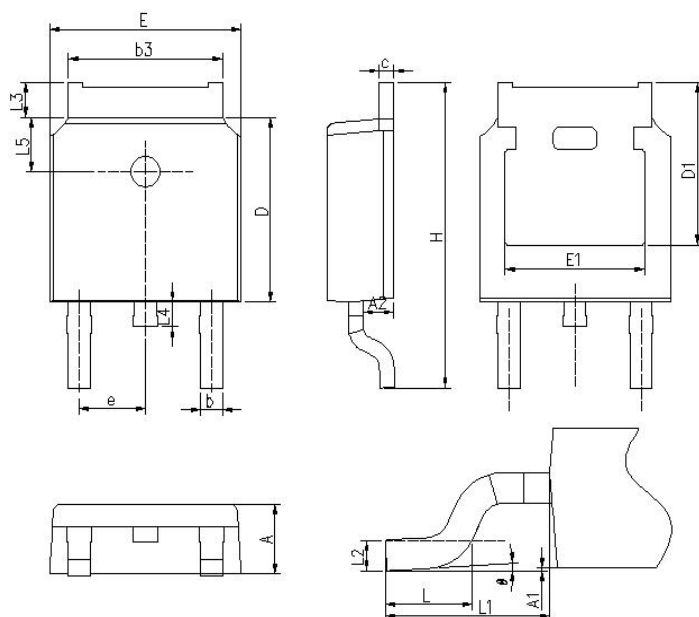


Figure 10 is a graph showing the power dissipation limits for the 2N7000 MOSFET. The x-axis represents the Drain-Source Voltage ( $V_{DS}$ ) in Volts (V), ranging from 1 to 1000. The left y-axis represents the Drain Current ( $I_D$ ) in Amperes (A), ranging from 0.01 to 10. The right y-axis represents the pulse width, with markers for 10 $\mu$ s, 100 $\mu$ s, 1ms, and 10ms. The graph shows two main regions: a DC region (labeled "DC") and a pulse region (labeled "Limited by  $R_{ds(on)}$ "). The DC region is bounded by a line that starts at approximately 0.3A at 1V and increases linearly to 10A at 100V. The pulse region is bounded by a line that starts at approximately 0.3A at 1V and increases linearly to 10A at 100V, then continues horizontally at 10A for  $V_{DS} > 100$  V. The graph is for Single pulse,  $T_c = 25^\circ\text{C}$ .

Figure 1 is a log-log plot showing the normalized transient thermal resistance  $Z_{\theta JC}$  (normalized) versus time  $t$ , Time (s). The y-axis ranges from  $10^{-3}$  to  $10^1$ , and the x-axis ranges from  $10^{-6}$  to  $10^{-1}$  seconds. Multiple curves are plotted for different duty cycles  $D$ : 0.01, 0.02, 0.05, 0.1, 0.3, 0.5, and 0.7. A curve for a 'single pulse' is also shown. The thermal resistance  $R_{\theta JC} = 1.57^\circ\text{C/W}$  is indicated. An inset shows a pulse waveform with peak power  $P_D$ , on-time  $T_{on}$ , and period  $T$ .

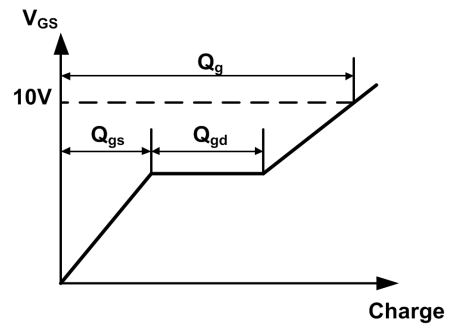
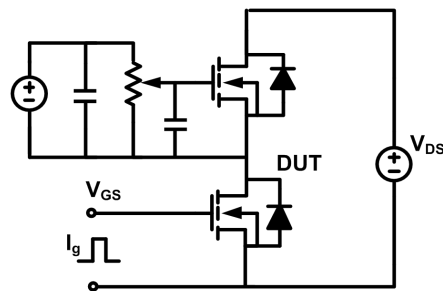
# Mechanical Dimensions for TO-252



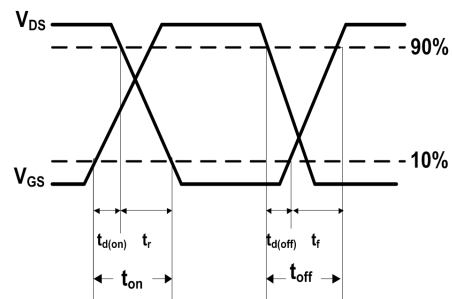
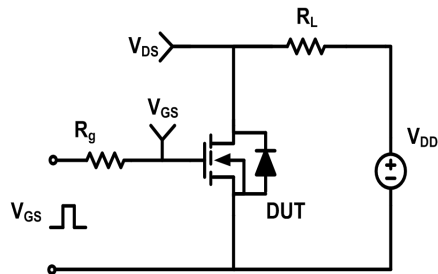
DIMENSIONS IN MILLIMETERS		
SYMBOL	MIN	MAX
A	2.18	2.4
A1	—	0.2
A2	0.9	1.17
b	0.65	0.9
b3	4.95	5.5
c	0.43	0.89
D	5.97	6.22
D1	5.21	—
E	6.35	6.8
E1	4.32	—
e	2.286BSC	
H	9.4	10.5
L	0.38	1.78
L1	2.90BSC	
L2	0.51BSC	
L3	0.88	1.28
L4	—	1.02
L5	1.65	1.95
θ	0°	10°

## Test Circuit & Waveforms

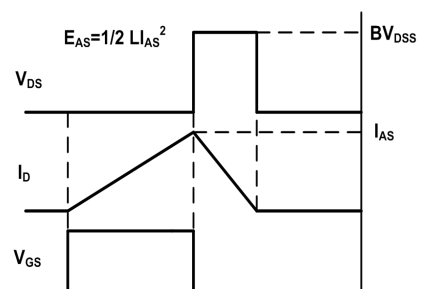
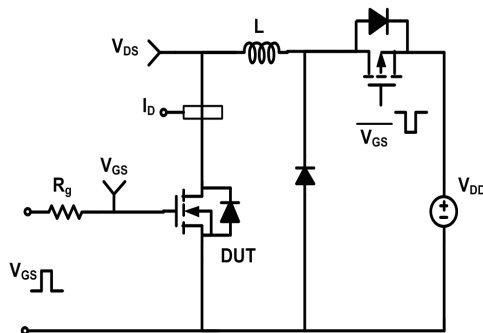
### Gate Charge Test Circuit & Waveform



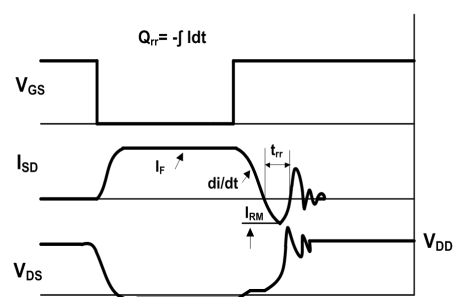
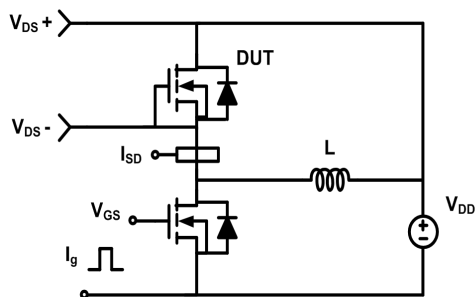
### Resistive Switching Test Circuit & Waveform



### Unclamped Inductive Switching (UIS) Test Circuit & Waveform



### Diode Recovery Test Circuit & Waveform



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## Version Information

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LNG5N50

Revision:2023-07-31,Rev 1.0

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